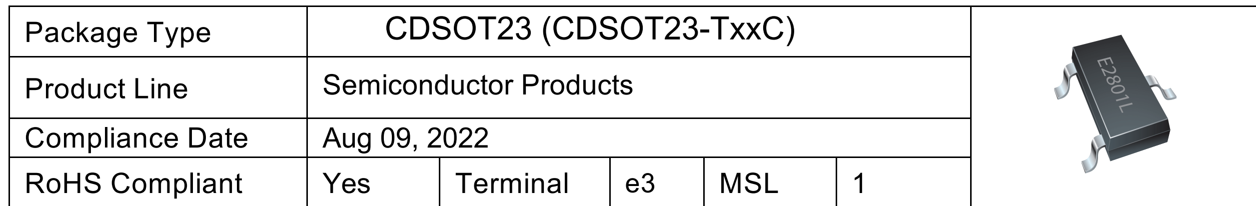
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-TxxC)				
Product Line	Semiconductor Products				
Compliance Date	Aug 09, 2022				
RoHS Compliant	Yes	Terminal	e3	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.00548573	Amorphous Silica	60676-86-0	87.600	49.8998	53.60294
				Epoxy Resin A	Proprietary	4.900	1.37824	
				Epoxy Resin B	29690-82-2	4.000	1.2413	
				Phenol Resin	Proprietary	3.000	0.8438	
				Carbon Black	1333-86-4	0.500	0.2398	
2	Leadframe	Copper Alloy	0.00394239	Copper	7440-50-8	97.100	37.4902	38.52243
				Iron	7439-89-6	2.289	0.77699	
				Phosphorus	7723-14-0	0.020	0.00157	
				Zinc	7440-66-6	0.100	0.0307	
				Lead	7439-92-1	0.010	0.00487	
				Silver	7440-22-4	0.481	0.2181	
3	Chip	Silicon	0.00042524	Silicon	7440-21-3	88.374	3.6721	4.1552
				Nickel	7440-02-0	5.913	0.2457	
				Aluminum	7429-90-5	5.347	0.2222	
				Gold	7440-57-5	0.366	0.0152	
4	Die Attach	Silver Epoxy	0.00011183	Silver	7440-22-4	75.000	0.9808	1.09273
				Epoxy resin	9003-36-5	19.900	0.0978	
				1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	3.000	0.0041	
				Aromatic polyamine	Proprietary	2.000	0.00986	
				Adipic acid	124-04-9	0.100	0.00017	
5	Bond Wires	Copper	0.00003032	Copper	7440-50-8	98.700	0.2911	0.2963
				Non - Cu element	Proprietary	1.300	0.0052	
6	Lead Finish	Matte Tin	0.00023849	Tin	7440-31-5	100.000	2.3304	2.3304
		Total Weight	0.0102340					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society